

Single 2-Input OR Gate

NLV74HC1G32

The NLV74HC1G32 is a high speed CMOS 2-input OR gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The NLV74HC1G32 output drive current is 1/2 compared to MC74HC series.

Features

- High Speed: $t_{PD} = 7 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- High Noise Immunity
- Balanced Propagation Delays ($t_{PLH} = t_{PHL}$)
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2 \text{ mA}$)
- Chip Complexity: < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

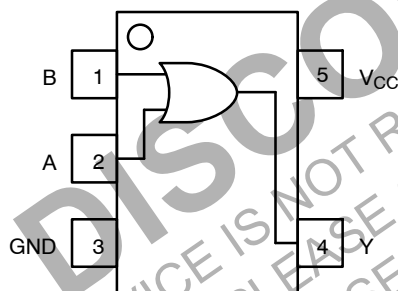


Figure 1. Pinout

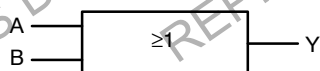
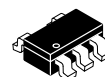


Figure 2. Logic Symbol

PIN ASSIGNMENT	
1	B
2	A
3	GND
4	Y
5	V _{CC}

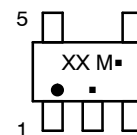
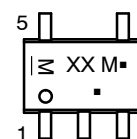


SC-88A
DF SUFFIX
CASE 419A



TSOP-5
DT SUFFIX
CASE 483

MARKING DIAGRAMS



XX = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	H

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0	V
V _{IN}	DC Input Voltage	−0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage	−0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current	±20	mA
I _{OK}	DC Output Diode Current	±20	mA
I _{OUT}	DC Output Source/Sink Current	±12.5	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin	±25	mA
T _{STG}	Storage Temperature Range	−65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	+150	°C
θ _{JA}	Thermal Resistance (Note 1)	SC-88A TSOP-5 377 320	°C/W
P _D	Power Dissipation in Still Air at 85°C	SC-88A TSOP-5 332 390	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34 UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model 2000 1000	V
I _{LATCHUP}	Latchup Performance (Note 3)A	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow per JESD51-7.
2. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued per JEDEC/JEP172A.
3. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	6.0	V
V _{IN}	DC Input Voltage	0.0	V _{CC}	V
V _{OUT}	DC Output Voltage	0.0	V _{CC}	V
T _A	Operating Temperature Range	−55	+125	°C
t _r , t _f	Input Rise and Fall Time			ns
	V _{CC} = 2.0 V	0	1000	
	V _{CC} = 3.0 V	0	600	
	V _{CC} = 4.5 V	0	500	
	V _{CC} = 6.0 V	0	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

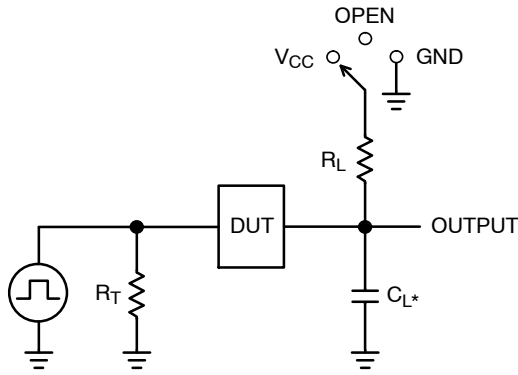
Symbol	Parameter	Test Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$		$-55^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20	— — — —	— — — —	1.5 2.1 3.15 4.20	— — — —	1.5 2.1 3.15 4.20	— — — —	V
V_{IL}	Low-Level Input Voltage		2.0 3.0 4.5 6.0	— — — —	— — — —	0.5 0.9 1.35 1.80	— — — —	0.5 0.9 1.35 1.80	— — — —	0.5 0.9 1.35 1.80	V
V_{OH}	High-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -20\text{ }\mu\text{A}$	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0	— — — —	1.9 2.9 4.4 5.9	— — — —	1.9 2.9 4.4 5.9	— — — —	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -2\text{ mA}$ $I_{OH} = -2.6\text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	— —	4.08 5.58	— —	
V_{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 20\text{ }\mu\text{A}$	2.0 3.0 4.5 6.0	— — — —	0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1	— — — —	0.1 0.1 0.1 0.1	— — — —	0.1 0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 2\text{ mA}$ $I_{OL} = 2.6\text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	0.33 0.33	— —	0.40 0.40	
I_{IN}	Input Leakage Current	$V_{IN} = 6.0\text{ V}$ or GND	6.0	—	—	± 0.1	—	± 1.0	—	± 1.0	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0	—	—	1.0	—	10	—	40	μA

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	T _A = 25°C			–40°C ≤ T _A ≤ 85°C		–55°C ≤ T _A ≤ 125°C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, (A or B) to Y	V _{CC} = 5.0 V C _L = 15 pF	–	3.5	15	–	20	–	25	ns
		V _{CC} = 2.0 V C _L = 50 pF	–	20	100	–	125	–	155	
		V _{CC} = 3.0 V	–	11	27	–	35	–	90	
		V _{CC} = 4.5 V	–	8	20	–	25	–	35	
		V _{CC} = 6.0 V	–	7	17	–	21	–	26	
t _{TLH} , t _{THL}	Output Transition Time	V _{CC} = 5.0 V C _L = 15 pF	–	3	10	–	15	–	20	ns
		V _{CC} = 2.0 V C _L = 50 pF	–	25	125	–	155	–	200	
		V _{CC} = 3.0 V	–	16	35	–	45	–	60	
		V _{CC} = 4.5 V	–	11	25	–	31	–	38	
		V _{CC} = 6.0 V	–	9	21	–	26	–	32	
C _{IN}	Input Capacitance		–	5	10	–	10	–	10	pF
C _{PD}	Power Dissipation Capacitance (Note 4)	Typical @ 25°C, V _{CC} = 5.0 V								pF
		10								

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

NLV74HC1G32



* C_L includes probe and jig capacitance
 R_T is Z_{OUT} of pulse generator (typically 50 Ω)
 $f = 1$ MHz

Figure 3. Test Circuit

Test	Switch Position	C_L , pF	R_L , Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table	X
t_{TLH} / t_{THL} (Note 5)	Open		X
t_{PLZ} / t_{PZL}	V_{CC}		1 k
t_{PHZ} / t_{PZH}	GND		1 k

X - Don't Care

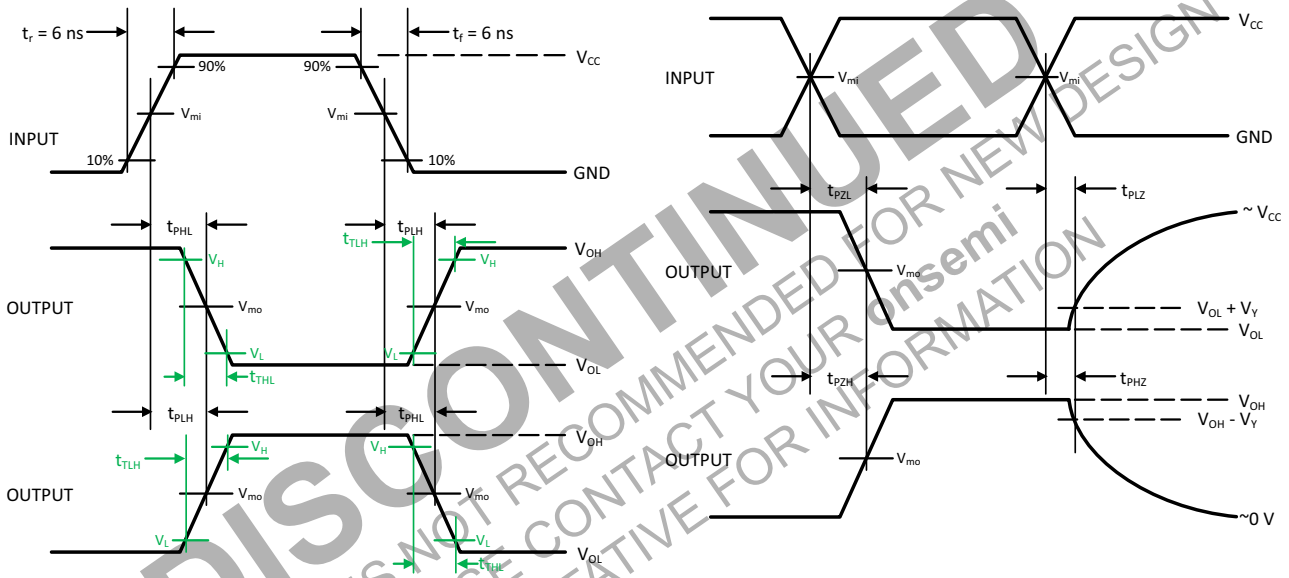


Figure 4. Switching Waveforms

V_{CC} , V	V_{mi} , V	V_{mo} , V		V_L , V	V_H , V	V_Y , V
		t_{PLH}, t_{PHL}	$t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}$			
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{OL} + 0.1 (V_{OH} - V_{OL})$	$V_{OL} + 0.9 (V_{OH} - V_{OL})$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{OL} + 0.1 (V_{OH} - V_{OL})$	$V_{OL} + 0.9 (V_{OH} - V_{OL})$	0.3

5. t_{TLH} and t_{THL} are measured from 10% to 90% of $(V_{OH} - V_{OL})$, and 90% to 10% of $(V_{OH} - V_{OL})$, respectively.

NLV74HC1G32

ORDERING INFORMATION

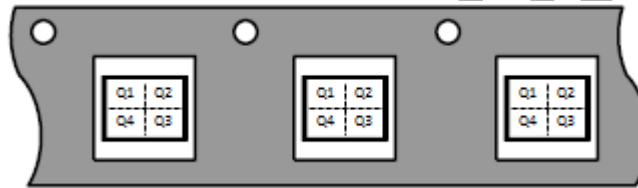
Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
MC74HC1G32DFT1G-L22038	SC-88A	H4	Q2	3000 / Tape & Reel
NLVHC1G32DFT1G*	SC-88A	H4	Q2	3000 / Tape & Reel
MC74HC1G32DFT2G-L22038	SC-88A	H4	Q4	3000 / Tape & Reel
NLVHC1G32DFT2G*	SC-88A	H4	Q4	3000 / Tape & Reel
MC74HC1G32DTT1G	TSOP-5	H4	Q4	3000 / Tape & Reel
NLV74HC1G32DTT1G*	TSOP-5	H4	Q4	3000 / Tape & Reel

[†]For complete information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PIN 1 ORIENTATION IN TAPE AND REEL

Direction of Feed





SCALE 2:1

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE M

DATE 11 APR 2023



RECOMMENDED
MOUNTING FOOTPRINT

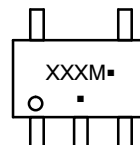
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.95	1.10
A1	---	---	0.10
A3	0.20 REF		
b	0.10	0.20	0.30
c	0.10	---	0.25
D	1.80	2.00	2.20
E	2.00	2.10	2.20
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.10	0.15	0.30

GENERIC MARKING
DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:

- PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 2:

- PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 3:

- PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 4:

- PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:

- PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6:

- PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

STYLE 7:

- PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:

- PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

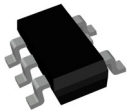
STYLE 9:

- PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

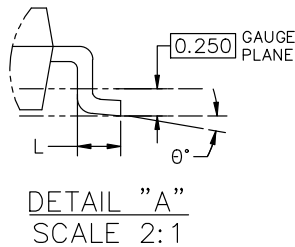
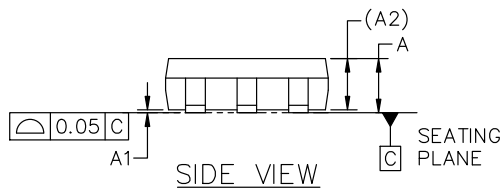
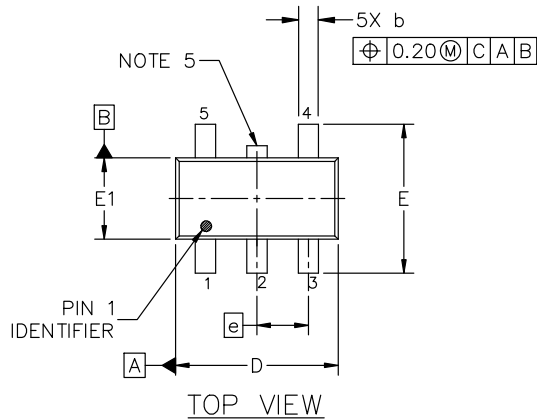
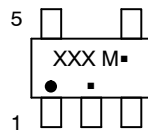
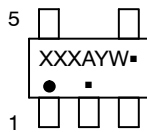
Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:	SC-88A (SC-70-5/SOT-353)	PAGE 1 OF 1

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TSOP-5 3.00x1.50x0.95, 0.95P
CASE 483
ISSUE P

DATE 01 APR 2024


GENERIC
MARKING DIAGRAM*


XXX = Specific Device Code XXX = Specific Device Code
A = Assembly Location M = Date Code
Y = Year ■ = Pb-Free Package
W = Work Week
■ = Pb-Free Package

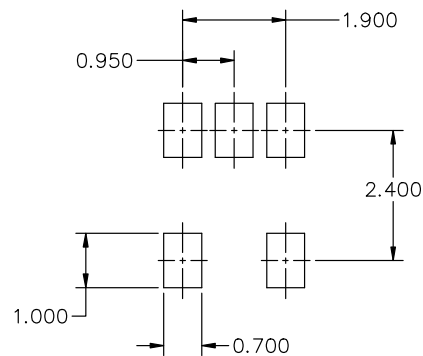
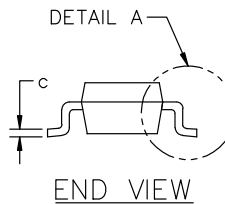
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES).
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D.
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.900	1.000	1.100
A1	0.010	0.055	0.100
A2	0.950 REF.		
b	0.250	0.375	0.500
c	0.100	0.180	0.260
D	2.850	3.000	3.150
E	2.500	2.750	3.000
E1	1.350	1.500	1.650
e	0.950 BSC		
L	0.200	0.400	0.600
θ	0°	5°	10°



* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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DESCRIPTION: TSOP-5 3.00x1.50x0.95, 0.95P

PAGE 1 OF 1

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